

Abstract

A porous polishing pad is useful for polishing semiconductor substrates. The porous polishing pad has a porous matrix formed from a coagulated polyurethane and a non-fibrous polishing layer. The non-fibrous polishing layer has a polishing surface with a pore count of at least 500 pores per mm² that decreases with removal of the polishing layer; and the polishing surface has a surface roughness Ra between 0.01 and 3 μm.